

## Recommended reflow soldering conditions

This package is surface mount device (SMD).

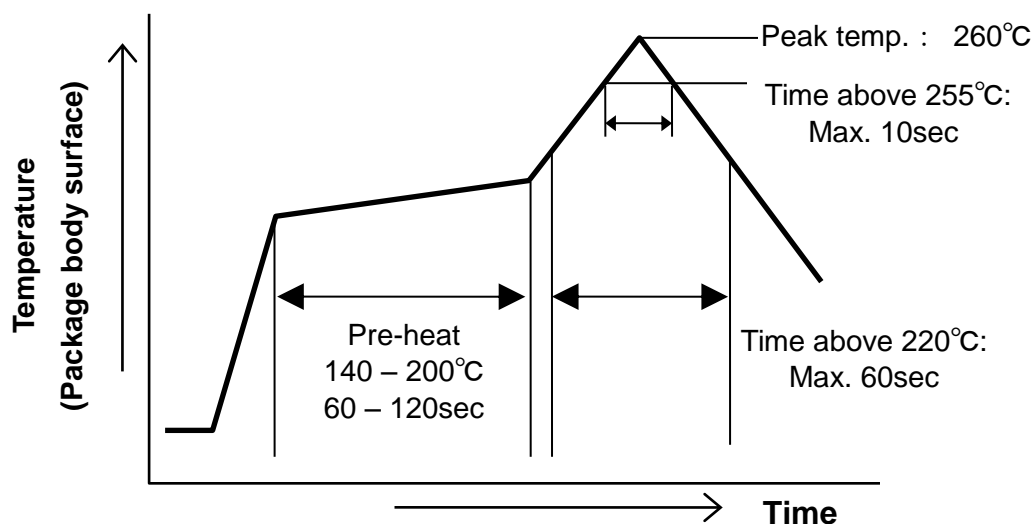
The resistance to soldering heat with SMD depends on storage conditions, soldering methods, and soldering conditions.

Please assemble packages according to the following conditions.

### Recommended storage conditions

	Conditions	Time
Before opening dry pack:	$\leq 30^{\circ}\text{C} 85\% \text{RH}$	1 year
After opening dry pack:	$\leq 30^{\circ}\text{C} 70\% \text{RH}$	1 year

### Recommended reflow profile



This package should be assembled with IR reflow, full convection, or IR/convection.

The allowable number of time with the reflow is max. 2 times. This must be done in the above-mentioned condition (after opening dry pack).

Nitrogen reflow is recommended to inhibit the effects of oxidation and improve wettability.

\* Hand soldering using a soldering iron should be performed under the following conditions:

<Temperature: less than 350 °C, Time: less than 5 sec, Times: twice or less>

Pay sufficient attention not to let a soldering iron contact any parts other than leads.

(Storage rank: MSL2)